Tool ID: 826
Tool Location: 224

Equipment Information Sheet

Disco Wafer Grinder

Manager: Christopher Alpha 607-254-4913 Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY
USAGE RESTRICTIONS
SCHEDULING/SIGN-UP RESTRICTIONS
MATERIALS COMPATIBILITY CATEGORY

Minimum Tool Time: 15 minutes

Tool Category 3: Silcion, III-V Compound Semiconductor, Glass and Metal Category

Allowed	Not Allowed
Tool category 1/1E and 2 materials	Glass Substrates
III/V compound Semiconductors allowed	No CNF Class A or Class B metals-and oxides/compounds of i.e. (Magnesium,Zinc, Barium, Calcium)
PECVD and ALD Films	No High Vapor pressure materials
Cured organics and baked Photoresist	
Organic/Bio Materials prepped w/o Salt Buffers	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

Last Updated: 05/28/2026